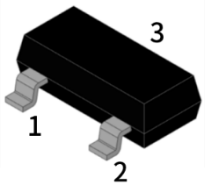
BAT54（A/C/S）LDT1

SCHOTTKY BARRIER DIODE

1.FEATURES

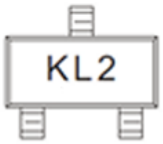
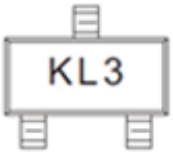
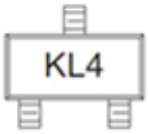
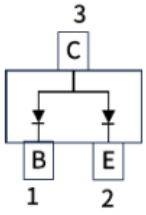
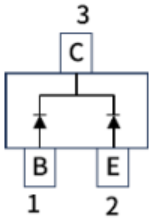
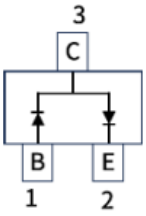
- The material of product compliance with RoHS requirements and Halogen Free.
- High Stability and High Reliability.
- Extremely Fast Switching Speed



SOT23 (TO-236)

2.Mechanical Data

- SOT-23 Small Outline Plastic Package.
- Tin plated leads, solderable per J-STD-002 and JESD22-B102.
- Marking:

BAT54A	BAT54C	BAT54S
		
KL2	KL3	KL4
		

3.ORDERING INFORMATION

Device	Min Pack	Inner Box	Outer Carton	Reel
BAT54（A/C/S）LDT1	3000	45000	180000	7 inch

4.MAXIMUM RATINGS (Ta = 25°C)

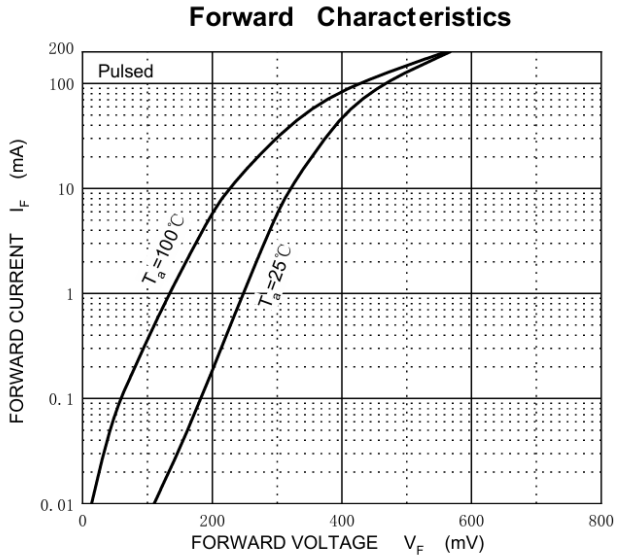
Parameter	Symbol	Limit	Unit
DC Blocking Voltage	VR	30	V
Forward Continuous Current	IFM	200	mA
Power Dissipation	PD	200	mW

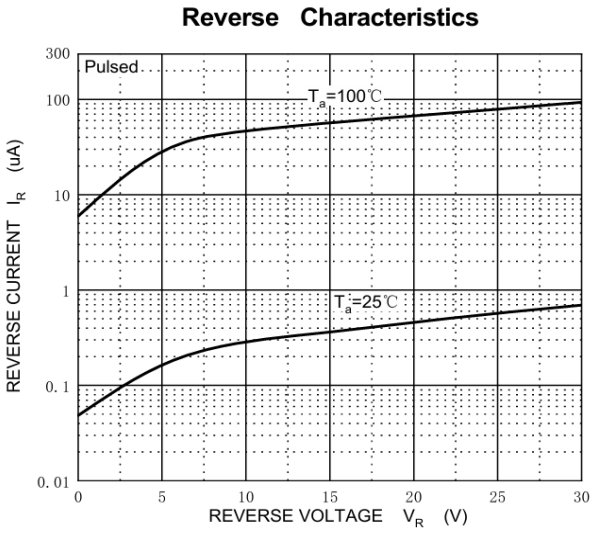
Storage temperature	TSTG	-55-125	℃

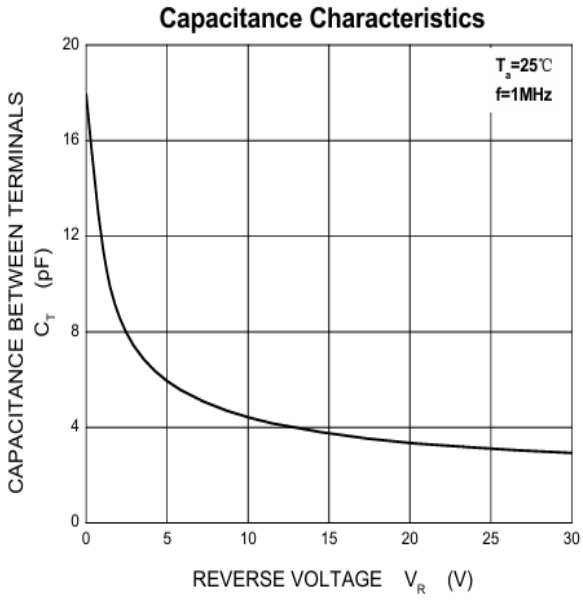
5.ELECTRICAL CHARACTERISTICS (Ta= 25ºC unless otherwise specified)

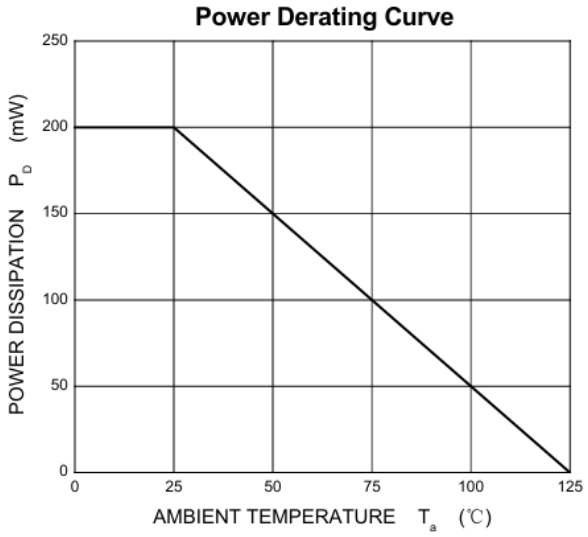
Parameter	Symbol	Condition	Min	TYP	Max	Unit
Reverse Voltage	V(BR)	IR=0.1mA	30			V
Forward Voltage	VF	IF=0.1mA			0.23	V
		IF=1mA			0.30	V
		IF=10mA			0.40	V
		IF=30mA			0.50	V
		IF=100mA			1	V
Reverse Voltage Leakage Current	IR	VR=25V	2			μA
Diode Capacitance	CD	VR=1V,f=1MHZ		10		PF
Reverse recovery time	trr	IF=IR=10mA,RL=100 Ω,IRR=0.1IR	5			ns

7.ELECTRICAL CHARACTERISTICS CURVES

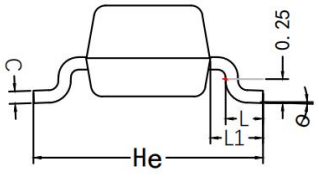


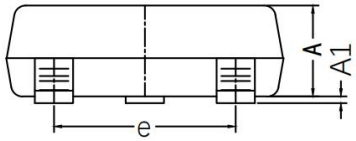


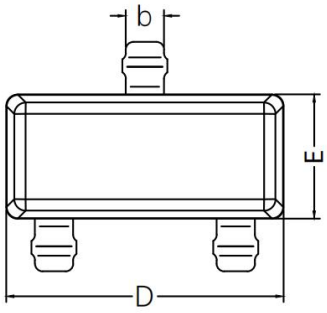




8.OUTLINE AND DIMENSIONS

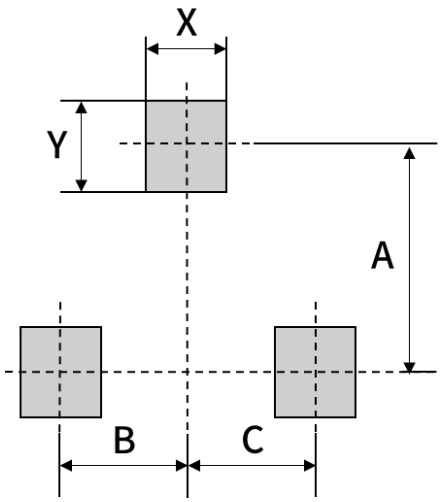






DIM	MIN	NOR	MAX
A	0.85	0.95	1.05
A1	0.01	0.06	0.10
b	0.36	0.44	0.52
c	0.09	0.13	0.18
D	2.80	2.90	3.10
E	1.20	1.30	1.40
e	1.78	1.90	2.04
L	0.30	0.40	0.50
L1	0.35	0.50	0.65
He	2.10	2.35	2.50
θ	0°	-	10°
All Dimensions in mm			

9.SUGGESTED PAD LAYOUT



SOT23		
DIM	mm	inch
A	2.00	0.079
B	0.95	0.037
C	0.95	0.037
X	0.80	0.031
Y	0.90	0.035

10.DISCLAIMER

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